



Material Content Data Sheet



Sales Product Name		BTS5090-1EJA		Issued		22. January 2018		
MA#		MA001611304						
Package		PG-DSO-8-43		Weight*		84.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.775	2.11	2.11	21058	21058
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		111	
	non noble metal	zinc	7440-66-6	0.038	0.04		446	
	non noble metal	iron	7439-89-6	0.752	0.89		8919	
wire	non noble metal	copper	7440-50-8	30.529	36.21	37.15	362139	371615
	non noble metal	copper	7440-50-8	0.361	0.43	0.43	4278	4278
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1154
encapsulation	plastics	epoxy resin	-	4.476	5.31		53090	
	inorganic material	silicondioxide	60676-86-0	44.074	52.27	57.70	522818	577062
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9654	9654
plating	noble metal	silver	7440-22-4	0.726	0.86	0.86	8612	8612
glue	plastics	epoxy resin	-	0.114	0.14		1351	
	noble metal	silver	7440-22-4	0.537	0.64	0.78	6370	7721
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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